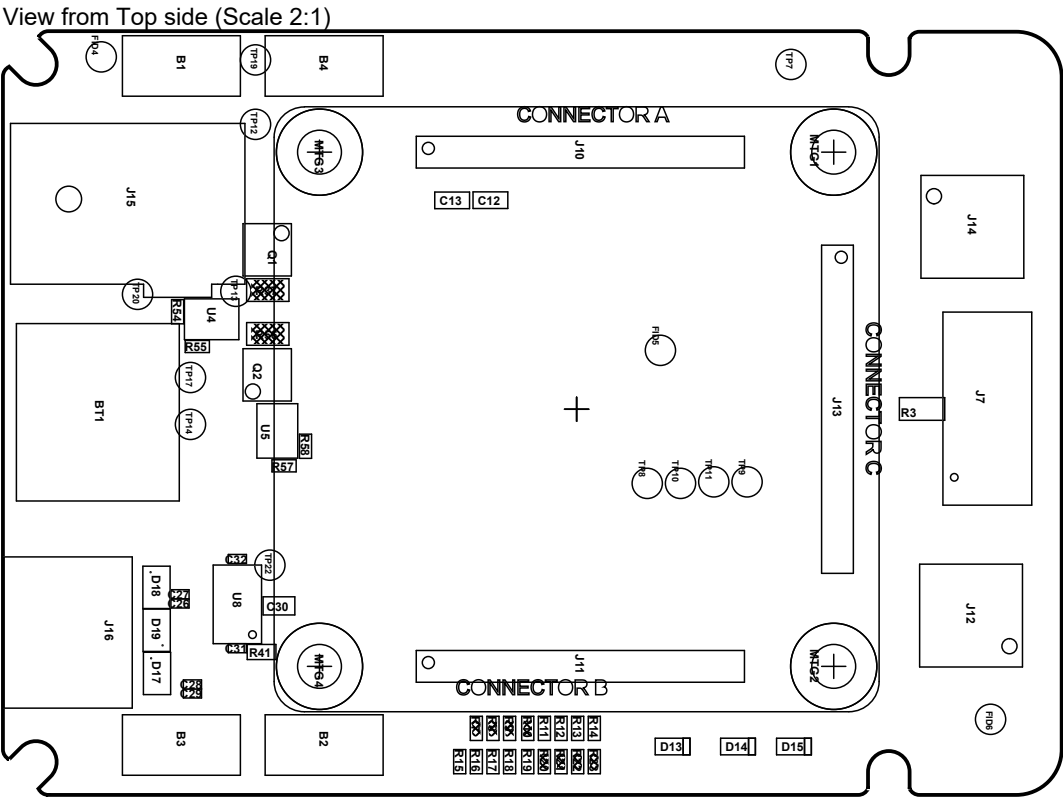


ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.



Title: DM3390
Number: D0000190 Revision: R0M0E0
Date: 16/05/2022 Sheet: 1 of 2
Drawn by: David Malovrh



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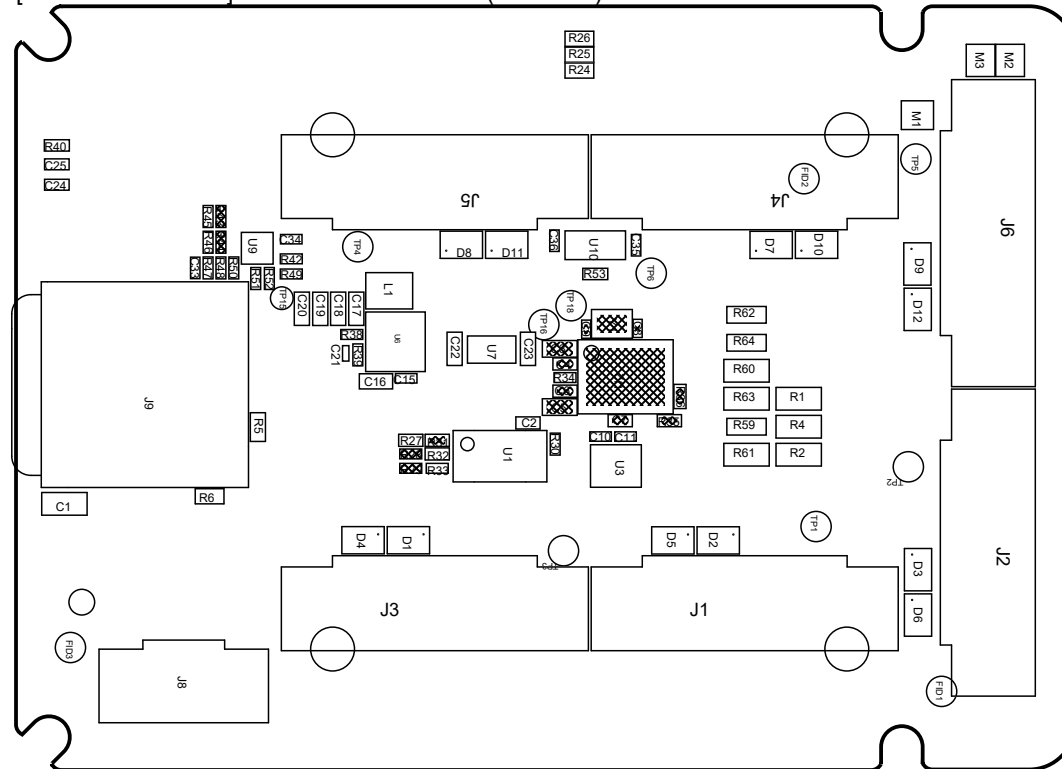
B

C

D

E

[Variant: Production] View from Bottom side (Scale 2:1)



Title: **DM3390**

Number: D0000190 Revision: R0M0E0

Date: 16/05/2022 Sheet: 2 of 2

Drawn by: David Malovrh

LUXonjs

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